

ABSTRACT

Provided is an adhesive tape for semiconductor processing having excellent processability, in which there is no occurrence of incisions or cracks caused by the impact at the time of transportation or the like, and even if the adhesive layer is stretched during a precutting process of processing the adhesive layer to a defined size, the adhesive layer does not crack. An adhesive tape for semiconductor processing (10) of the invention has an adhesive layer (13) and a tacky adhesive sheet (15) laminated together, in which the adhesive layer (13) has a tear strength (A) according to the right angled tear method defined in JIS K7128-3, of 0.8 MPa or more, and a tear strength (C) according to the right angled tear method defined in JIS K7128-3 at -15°C, of 0.8 MPa or less.